ADI Known Good Die (KGD)

ADI KGD

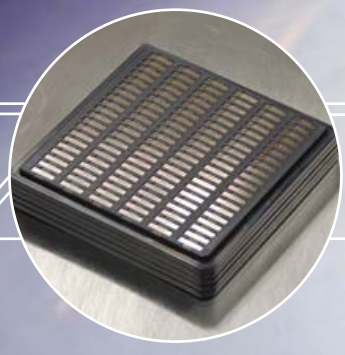
Capability:

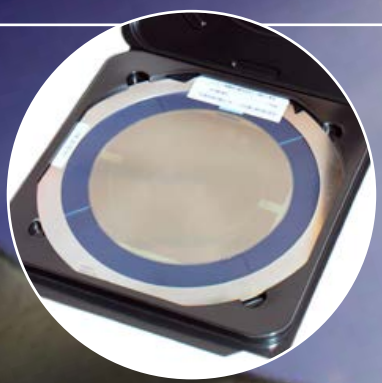
- Tested to Full Data Sheet Specs (Zero PPM)
- Probing at Temperature (-60°C >190°C)
- Die Thicknesses from 70µm
- Die Sizes from 500µm^2
- Full Traceability for each Die Shipped
- Auto Inspection Options
- Outlier Removal Options

Shipping Options:

- Reconstituted Die on Film Frame
- Sawn Wafer on Film Frame
- Waffle Pack
- Tape and Reel

- Certified to ISO9001:2008 and ISO/TS16949





ANALOG DEVICES

ADI Turnkey Known Good Die (KGD)

In today's technologically driven world there is an ever-increasing demand for portable, hand-held, reduced-scale electronic equipment. Products tend to be lighter, thinner and faster, but their functionality continues to expand and develop at high intensity.

This drive for miniaturisation of portable products, in conjunction with decreased cost requirements and space reduction in larger products, is paving the way not only for Wafer Level Chip Scale packages (WLCSP), Flip Chips etc., but also, Bare Die. Customer demand for increased reliability has greatly contributed to the requirement of what is termed: Known Good Die (KGD).

ADI has been offering Known Good Die (KGD) since mid 2006. Our KGD processes allow for the shipment of product in die format to exceptionally high quality and reliability standards.

The objective of KGD is to supply die products that meet full product specification (at-speed function test, burn-in process and PPM level defects, over the entire temperature range).
The innovative Known Good Die manufacturing process at ADI is an ideal solution for customers whose applications demand zero defects. ADI employs a unique delivery process whereby KGD parts are tested to Full Data Sheet Specification, post singulation.

Refer to link below for the full listing of ADI released KGD products. Please note: The majority of ADI's Standard Product Portfolio can be provided in KGD Format.

http://mil-aero.analog.com/static/imported-files/microsites/Mil_Aero/KnownGoodDie.pdf

If you require a KGD Part please email:
KGD_Sales_Support@analog.com

- Wafer Fab
- Back Grind and Saw
- 100% Electrical Probe/Test
- Part Average Testing
- 100% Auto Inspection
- Pick and Place
- Reconstituted Die on Film, Sawn Wafer on Film, Waffle Pack, Tape and Reel
- KGD to Customer

Portfolio Snapshot:

Generic	Material	Temp Range	Status	Description
ADG841	ADG841-KGD-CHIPS	-40°C to 125°C	Released	0.28 Ω CMOS 1.65 V to 3.6 V Single SPST Switches in SC70 Closed for a Logic 1 Input
AD7924	AD7924-KGD-DF	-40°C to 85°C	Released	4-Channel, 1 MSPS, 12-Bit A/D Converter with Sequencer in 16-Lead TSSOP
AD7466	AD7466-KGD-DF	-40°C to 85°C	Released	1.6 V Micro-Power 12-Bit ADC
AD8229	AD8229-KGD-CHIPS	-40°C to 210°C	Released	1nV/√Hz Low Noise 210°C Instrumentation Amplifier
AD8028	AD8028-KGD-CHIPS	-40°C to 125°C	Released	Low Distortion, High Speed Rail-to-Rail Input/Output Amplifier
AD8065	AD8065-KGD-CHIPS	-40°C to 85°C	Released	High Performance, 145 MHz FastFET™ Op Amp
ADT7517	ADT7517-KGD-DF	-40°C to 125°C	In process	SPI-/I2°C Compatible, Temperature Sensor, 4-Channel ADC and Quad Voltage Output
AD8202	AD8202W-KGD-R7	-40°C to 125°C	In process	High Common-Mode Voltage, Single-Supply Difference Amplifier
ADA4897-2	ADA4897-2-KGD-CHIPS	-40°C to 125°C	In process	1nV/√Hz Low Power Operational Amplifier